

| Radiation | Type | Technology | Electrodes |
|-----------|------|--------------------------------------|------------------|
| Blue | | InGaN/Al ₂ O ₃ | Both on top side |

| | |
|--|--|
| | typ. dimensions (μm) |
| | <u>typ. thickness</u> 100 (± 10) μm <u>p and n contact</u> gold alloy <u>backside metalization</u> gold alloy |

Optical and Electrical Characteristics

T_{amb} = 25°C, unless otherwise specified

| Parameter | Test conditions | Symbol | Min | Typ | Max | Unit |
|---------------------------------|-------------------------|---------------------------------|------|------|-----|------|
| Forward voltage | I _F = 20 mA | V _F | | 2.7 | 3.1 | V |
| Forward voltage ² | I _F = 350 mA | V _F | | 3.5 | | V |
| Reverse voltage | I _R = 10 μA | V _R | 5V | | | V |
| Radiant power ¹ | I _F = 20 mA | Φ _e | 14 | 18 | | mW |
| Radiant power ¹ | I _F = 350 mA | Φ _e | 200 | 250 | | mW |
| Luminous intensity ¹ | I _F = 350 mA | I _v | 1500 | 2500 | | mcd |
| Peak wavelength | I _F = 350 mA | λ _P | 445 | 455 | 465 | nm |
| Dominant wavelength | I _F = 350 mA | λ _D | 455 | 465 | 475 | nm |
| Spectral bandwidth at 50% | I _F = 20 mA | Δλ _{0.5} | | 25 | | nm |
| Switching time | I _F = 20 mA | t _r , t _f | | 50 | | ns |

¹Measured on bare chip with EPIGAP equipment

Labeling

| Type | Lot N° | I _v (typ) [mcd] | V _F (typ) [V] | Quantity |
|--------------|--------|----------------------------|--------------------------|----------|
| ELC-460-31-2 | | | | |

Packing: Chips on adhesive film with wire-bond side on top

We reserve the right to make changes to improve technical design and may do so without further notice.
 Parameters can vary in different applications. All operating parameters must be validated for each application by the customers themselves.